



Material Content Data Sheet



Sales Product Name		BGB 707L7ESD E6327		Issued		29. August 2013		
MA#		MA000668472						
Package		PG-TSLP-7-1		Weight*		1.58 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.11		1091	
	noble metal	gold	7440-57-5	0.007	0.42		4233	
	inorganic material	silicon	7440-21-3	0.049	3.14	3.67	31369	36693
leadframe	non noble metal	nickel	7440-02-0	0.329	20.86	20.86	208636	208636
wire	noble metal	gold	7440-57-5	0.046	2.94	2.94	29354	29354
encapsulation	organic material	carbon black	1333-86-4	0.011	0.69		6852	
	plastics	epoxy resin	-	0.146	9.25		92497	
	inorganic material	silicondioxide	60676-86-0	0.923	58.57	68.51	585816	685165
leadfinish	noble metal	gold	7440-57-5	0.032	2.01	2.01	20076	20076
plating	noble metal	gold	7440-57-5	0.032	2.01	2.01	20076	20076
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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